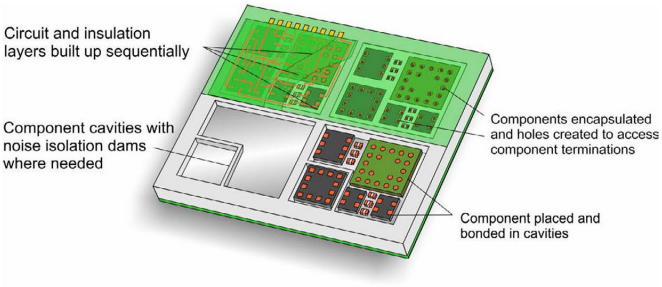
Occam Solderless Interconnect Process

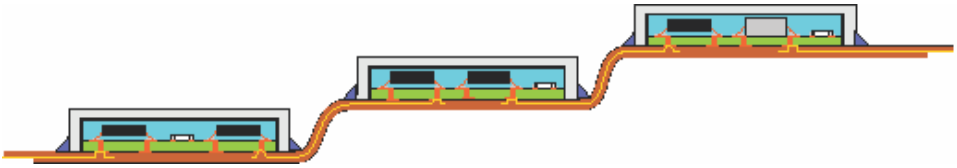
What is Occam?

The Occam process represents a transformative approach to electronics manufacturing by fundamentally inverting the traditional workflow. Instead of fabricating a printed circuit board (PCB) and subsequently soldering components onto it, the process begins by creating a "component board," where components are precisely positioned, securely affixed, and coated. The interconnecting circuits are then built up directly upon these components without solder or adhesive bonding



Solder joints, mounting pads, and high temperature reflow elimination

Components are placed in a carrier with contacts pointed up. The carrier can be a temporary assembly fixture or permanently attached to the components such as a heatsink, product case, or protective cover. The printed circuit board is then built-up onto the contacts.



Benefits:

- Maximum assembly temperature <200C
- Elimination of solder joint reliability issues.
- Reduced component to interconnect length, lower loss interconnect
- Wire bond wire elimination
- Increase component density by the elimination of mounting pads
- Compatible with convention HDI PCB and AME printed electronics interconnect
- Rigid, flexible and rigid-flex constructions

Applications:

- IOT
- Sensors
- Component Packages
- Portable electronics

Contact:

The Occam Group
+1 916-337-4402
http://theoccamgroup.com